



US 20230232089A1

(19) **United States**

(12) **Patent Application Publication**
Crow et al.

(10) **Pub. No.: US 2023/0232089 A1**

(43) **Pub. Date: Jul. 20, 2023**

(54) **HEATSINKS FOR AN IMAGE CAPTURE DEVICE**

Publication Classification

(51) **Int. Cl.**

H04N 23/52 (2006.01)

H04N 23/51 (2006.01)

(52) **U.S. Cl.**

CPC **H04N 23/52** (2023.01); **H04N 23/51** (2023.01)

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(21) Appl. No.: **18/188,977**

(57)

ABSTRACT

(22) Filed: **Mar. 23, 2023**

Related U.S. Application Data

(63) Continuation of application No. 17/490,302, filed on Sep. 30, 2021, now Pat. No. 11,637,949, which is a continuation of application No. 16/846,033, filed on Apr. 10, 2020, now Pat. No. 11,146,711.

An image capture device including first and second heat-sinks and a printed circuit board that separates the first and second heat-sinks and includes a processor configured to generate heat. The image capture device includes a conductor assembly that is configured to transfer heat by conduction and extends between the first heatsink, the processor, and the second heatsink.

